

# 2009 IEEE MTT-S International Microwave Symposium

7-12 June, Boston Convention and Exhibition Center  
IEEE Microwave Theory and Techniques Society



## MicroApps Seminar Call for Papers

The Microwave Application Seminars (MicroApps) at the IEEE MTT-S International Microwave Symposium 2009 (IMS2009) will be held in Boston, Massachusetts, Tuesday, June 7 through Thursday, June 9, 2009. Exhibitors are invited to submit applications engineering technical papers describing state-of-the-art products and processes of interest to the microwave community

**Electronic Paper Submission:** Technical papers for this symposium must be submitted via email to [microapps@ims2009.org](mailto:microapps@ims2009.org).

### Electronic Submission Deadlines

Abstracts for Review:

December 15, 2008

Final Manuscripts (CD ROM):

March 1, 2009

All Submissions must be made through email

[microapps@ims2009.org](mailto:microapps@ims2009.org)

### All submissions must be in PDF form; hard copies will not be accepted

#### A Paper Submission consists of:

1. Author information: name(s), title(s), affiliation, telephone # and email address.
2. A 30- 50 word abstract (in English) in PDF (Acrobat V6.0 or newer) format. No zip files. Describe the product or process, its importance to the microwave community and how it advances the state-of-the-art in an application.
3. Preferred length of presentations (multiples of 20 minutes, see note below).
4. A statement using the company letterhead authorizing IMS2009 to print your abstract and to record and publish your technical presentation on a limited access website and CD ROM if your paper is selected.

The decision to accept a paper for presentation at the seminar is based on this summary and confirmation that your affiliation is a registered exhibitor at IMS2009.

**Paper Selection Criteria:** All submissions are reviewed by the MicroApps Committee. The selection process will consider originality, clarity and interest to MTT-S members. Papers may cover new products, noteworthy state-of-the-art components, new technologies, manufacturing and design techniques incorporating the exhibitor's products and technologies. Presentations are typically 20 minutes in length; multiples of 20 minutes are encouraged for tutorial and educational purposes. Time allocations for each paper will be set by the committee.

The presentations will be made in the MicroApps Theater on the exhibit floor. Papers are open to all IMS registrants and should appeal to exhibit attendees.

Each exhibitor is invited to submit abstracts proposing applications presentations. The committee will review all submissions against the selection criteria and schedule accepted papers within available MicroApps session time.

A MicroApps CD, including all presentations, is provided free of charge to all MicroApps participants. Final presentation files for the CD are required by March 3, 2009 and must not exceed 15MB. Presentations are by digital projection using the session PC. PowerPoint is preferred. Voice recordings will be made as the slides are presented during the session and combined with the slides in video form.

#### Notification:

Authors will be notified of the evaluation results in January 2009.

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## MicroApps Areas of Interest

### CAD and Modeling Products and Techniques

- Design for Testability
- Design for Manufacturability
- System Design

### Mechanical and Passive Components

- Transmission Lines
- Filters and Multiplexers
- Ferrite and Acoustic Components
- Conventional Passive Devices
- MEMS

### Active Components

- Digital and Mixed Signal Circuits
- Oscillators and Frequency Sources
- RF Power Devices and Amplifiers
- Low Noise Receivers and Components
- Monolithic Microwave Integrated Circuits
- New Semiconductor Technologies
- Optoelectronics for Microwave/Millimeter-wave Applications
- Superconducting Components and technology
- Switches, Phase Shifters, Limiters, Mixers, Frequency Multipliers

### Sub-Assemblies

- Hybrids and Modules
- Microwave Systems
- Wireless and Cellular Communications
- Broadband Communication
- Sensors and Sensor Systems
- RFID

### Instrumentation and Measurement Techniques

- Novel Testing Techniques
- Assembly Test Techniques
- Basic RF and Microwave Test Procedures
- Wafer and Die RF Probe
- Extreme Environments Evaluation

### Packaging and Interconnects

### Manufacturing Processes

The theme of this year's MicroApps is to re-connect our more experienced engineers with younger engineers. Therefore, tutorials and papers on basic techniques that many use, but many more may be unfamiliar with are strongly solicited.

Also note that MicroApps papers are limited to exhibitors at IMS2009.